

Multilayer Ceramic Chip Capacitors

Product Top Page	Search by Part No.	Search by Characteristics	Cross Reference	Catalog	Tech Notes
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C2012X7R2A102K085AA



TDK item description ? C2012X7R2A102KT****

Applications

Commercial Grade
Please refer to Part No. [CGA4F2X7R2A102K085AA](#) for Automotive use.

Feature

Mid Mid Voltage (100 to 630V)

Series

C2012 [EIA 0805]

Status

Production (Not Recommended for New Design)

PDF file of this page

Contact



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Images are for reference only and show exemplary products.

Size

Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	0.85mm ±0.15mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics

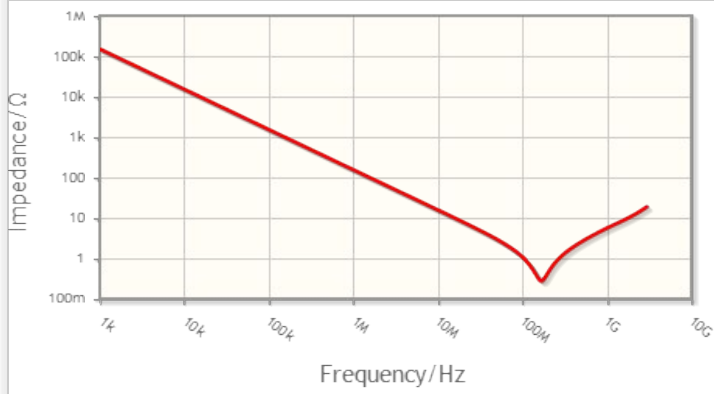
Capacitance	1nF ±10%
Rated Voltage	100VDC
Temperature Characteristic ?	X7R(±15%)
Dissipation Factor (Max.)	3%
Insulation Resistance (Min.)	10000MΩ

Other

Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

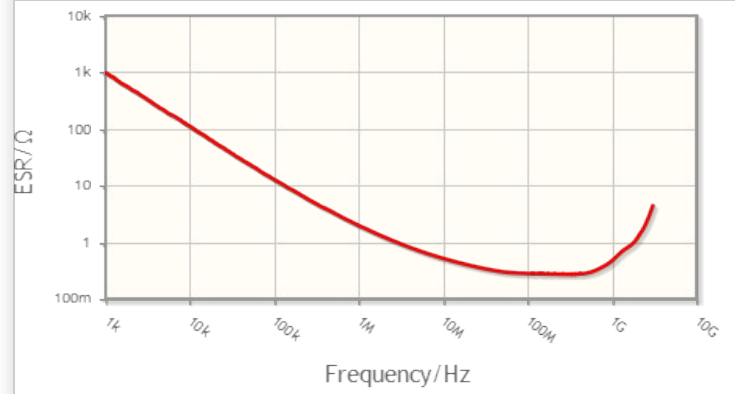
Impedance



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Change settings

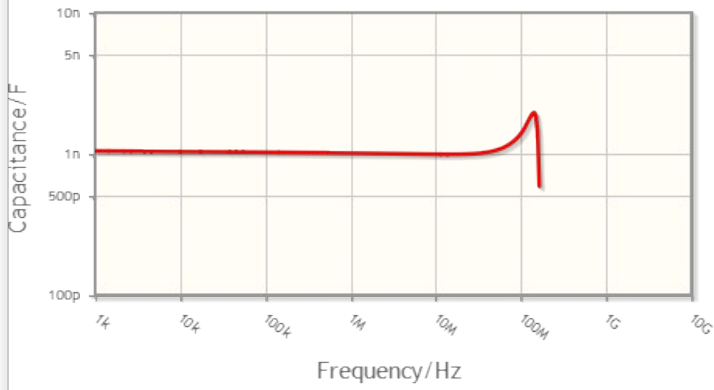
ESR



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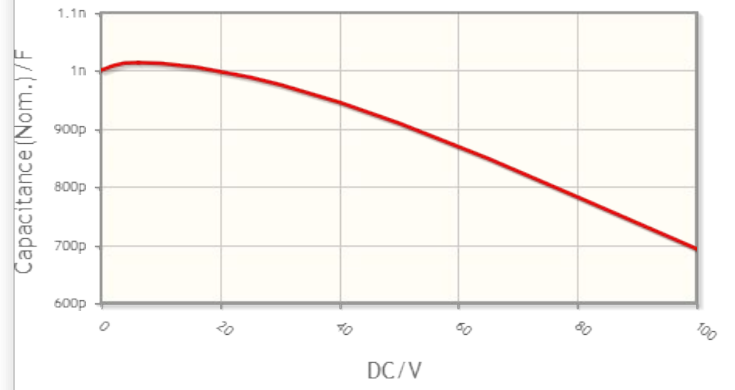
Capacitance



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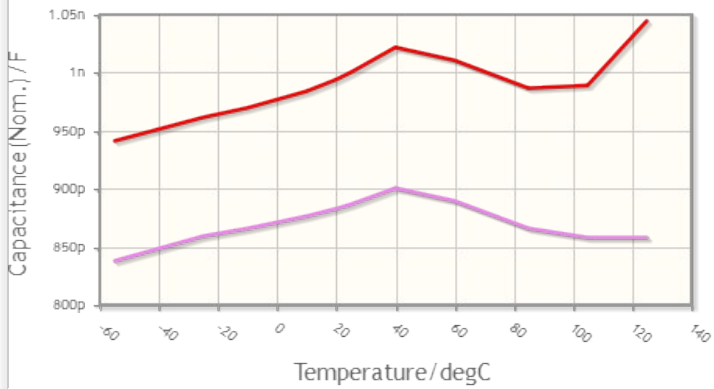
DC Bias Characteristic



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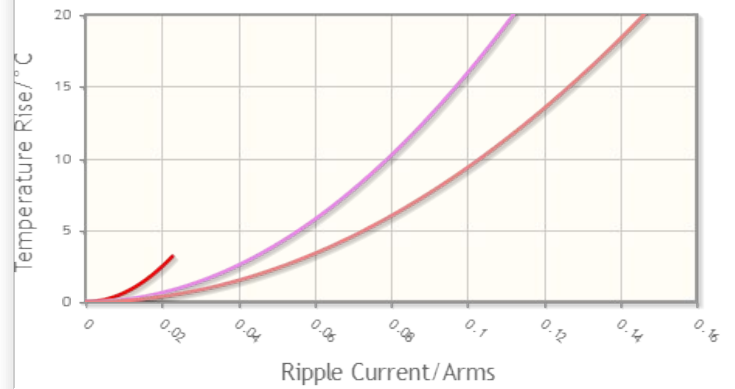
Temperature Characteristic



C2012X7R2A102K085AA(No Bias) C2012X7R2A102K085AA(DC Bias = 50V)

Change settings

Ripple Temperature Rising



C2012X7R2A102K085AA(100k Hz) C2012X7R2A102K085AA(500k Hz) C2012X7R2A102K085AA(1M Hz)

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